

Current Sensor

Current Sense Amplifier

BD14215FVJ-LA

General Description

The BD14215FVJ-LA current sense amplifier.
 This is the product guarantees long time support in Industrial market.
 This device operates from a single 2.7 V to 5.5 V power supply.
 It has wide common mode voltage range from -0.2 V to +26 V, outputs analog voltage. The gain is 20 V/V.
 The matched gain resistor minimizes gain error and realizes low offset voltage.
 The input bias current is 1 μ A (Typ) at typical condition.
 There is no need to adjust the gain error.

Features

- Long Time Support Product for Industrial Applications
- Wide Common Mode Voltage Range
- High Accuracy
- Low Offset Voltage
- Low Input Bias Current

Applications

- Industrial Equipment
- Telecom Equipment
- Over Current Detection

Key Specifications

- VDD Voltage Range: 2.7 V to 5.5 V
- Quiescent Current: 310 μ A (Typ)
- Common Mode Voltage Range: -0.2 V to +26 V
- Gain: 20 V/V (Typ)
- Gain Accuracy: ± 1.0 % (Max)
- Operating Temperature Range: -40 $^{\circ}$ C to +125 $^{\circ}$ C

Package

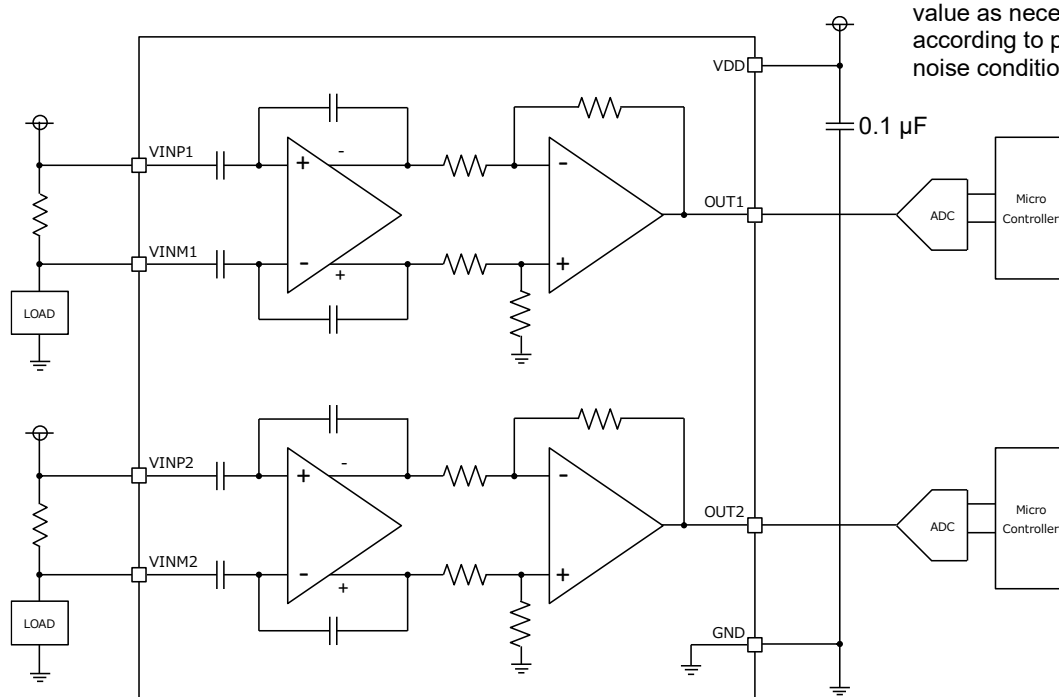
TSSOP-B8J

W (Typ) x D (Typ) x H (Max)

3.0 mm x 4.9 mm x 1.1 mm



Typical Application Circuit



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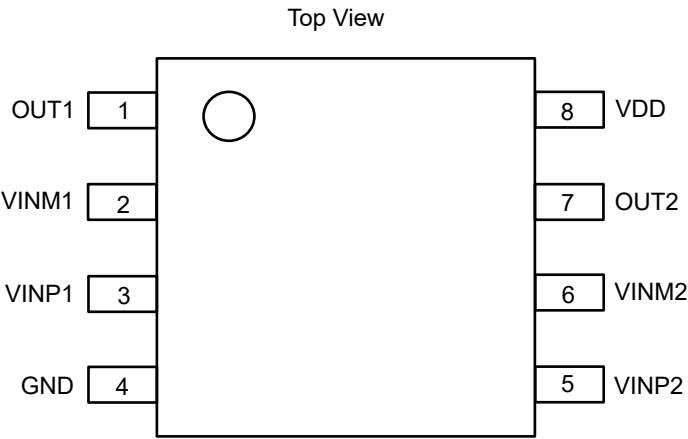
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Pin Descriptions



Pin Configurations

Pin No.	Pin Name	Function
1	OUT1	Current detection output for Channel 1
2	VINM1	Input of load side of shunt resistor for Channel 1
3	VINP1	Input of supply side of shunt resistor for Channel 1
4	GND	Ground
5	VINP2	Input of supply side of shunt resistor for Channel 2
6	VINM2	Input of load side of shunt resistor for Channel 2
7	OUT2	Current detection output for Channel 2
8	VDD	Power supply ^(Note 1)

(Note 1) Dispose a bypass capacitor between VDD and GND.

Absolute Maximum Ratings (Ta = 25 °C)

Parameter	Symbol	Rating	Unit
Power Supply Voltage	V _{DD}	7.0	V
Common Mode Voltage	V _{CM}	-0.2 to +26	V
Input Voltage	V _{IN}	-0.3 to V _{DD} +0.3	V
Storage Temperature Range	T _{stg}	-55 to +150	°C
Maximum Junction Temperature	T _{jmax}	150	°C

Caution 1: Operating the IC over the absolute maximum ratings may damage the IC. The damage can either be a short circuit between pins or an open circuit between pins and the internal circuitry. Therefore, it is important to consider circuit protection measures, such as adding a fuse, in case the IC is operated over the absolute maximum ratings.

Caution 2: Should by any chance the maximum junction temperature rating be exceeded the rise in temperature of the chip may result in deterioration of the properties of the chip. In case of exceeding this absolute maximum rating, design a PCB with thermal resistance taken into consideration by increasing board size and copper area so as not to exceed the maximum junction temperature rating.

Thermal Resistance (Note 2)

Parameter	Symbol	Thermal Resistance (Typ)		Unit
		1s ^(Note 4)	2s2p ^(Note 5)	
TSSOP-B8J				
Junction to Ambient	θ _{JA}	253.8	151.6	°C/W
Junction to Top Characterization Parameter ^(Note 3)	Ψ _{JT}	35	23	°C/W

(Note 2) Based on JESD51-2A (Still-Air).

(Note 3) The thermal characterization parameter to report the difference between junction temperature and the temperature at the top center of the outside surface of the component package.

(Note 4) Using a PCB board based on JESD51-3.

(Note 5) Using a PCB board based on JESD51-7.

Layer Number of Measurement Board	Material	Board Size
Single	FR-4	114.3 mm x 76.2 mm x 1.57 mmt

Top	
Copper Pattern	Thickness
Footprints and Traces	70 μm

Layer Number of Measurement Board	Material	Board Size
4 Layers	FR-4	114.3 mm x 76.2 mm x 1.6 mmt

Top		2 Internal Layers		Bottom	
Copper Pattern	Thickness	Copper Pattern	Thickness	Copper Pattern	Thickness
Footprints and Traces	70 μm	74.2 mm x 74.2 mm	35 μm	74.2 mm x 74.2 mm	70 μm

Recommended Operating Conditions

Parameter	Symbol	Min	Typ	Max	Unit	Condition
Power Supply Voltage	V_{DD}	2.7	-	5.5	V	
Common Mode Voltage	V_{CM}	-0.2	-	+26	V	VINP1, VINM1, VINP2, VINM2
Operating Temperature	T_{opr}	-40	+25	+125	°C	

Electrical Characteristics

(Unless otherwise specified $V_{DD} = 5\text{ V}$, $V_{CM} = 12\text{ V}$, $V_{SENSE} = (V_{VINP} - V_{VINM})$, $T_a = 25\text{ °C}$)

Parameter	Symbol	Min	Typ	Max	Unit	Condition
Power Supply						
Quiescent Current	I_{DD}	-	310	480	μA	$V_{SENSE} = 0\text{ mV}$
Current Sense Amplifier						
Offset Voltage	V_{OS}	-	-	±0.6	mV	$RTI^{(Note\ 6)}$, $V_{SENSE} = 0\text{ mV}$
Gain	G_{AIN}	-	20	-	V/V	
Gain Accuracy	G_{ERR}	-	-	±1.0	%	$V_{OUT} = 0.5\text{ V to }V_{DD}-0.5\text{ V}$ $T_a = -40\text{ °C to }+125\text{ °C}$
Nonlinearity Error	L_{in}	-	±0.01	-	%	$V_{OUT} = 0.5\text{ V to }V_{DD}-0.5\text{ V}$
Input Bias Current	I_{VINM}	-	1.0	-	μA	$V_{SENSE} = 0\text{ mV}$ $T_a = -40\text{ °C to }+125\text{ °C}$
High-level Output Voltage	V_{OUT_H}	$V_{DD} - 0.03$	-	-	V	OUT, $R_L = 10\text{ K}\Omega$ pulldown
Low-level Output Voltage	V_{OUT_L}	-	-	GND + 0.05	V	OUT, $R_L = 10\text{ K}\Omega$ pullup

(Note 6) RTI = Referred To Input

Typical Performance Curves

(Unless otherwise specified $V_{DD} = 5\text{ V}$, $V_{CM} = 12\text{ V}$, $V_{SENSE} = (V_{VINP} - V_{VINM})$, $T_a = 25\text{ }^{\circ}\text{C}$)

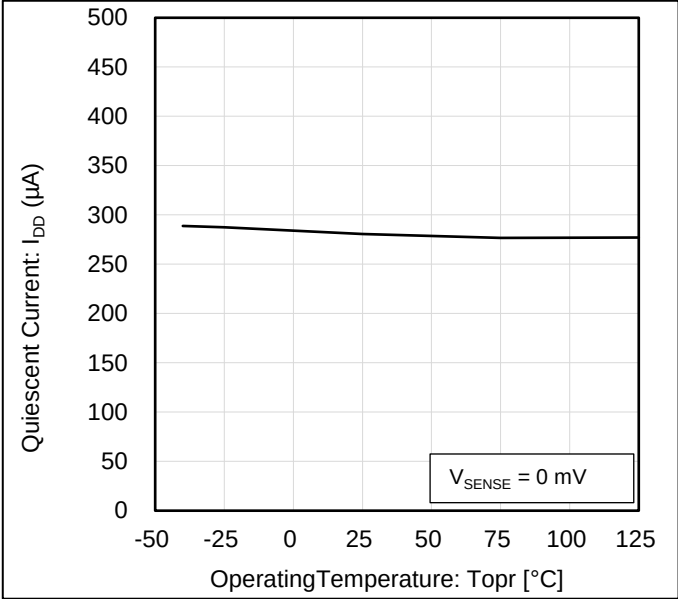


Figure 1. Quiescent Current vs Operating Temperature

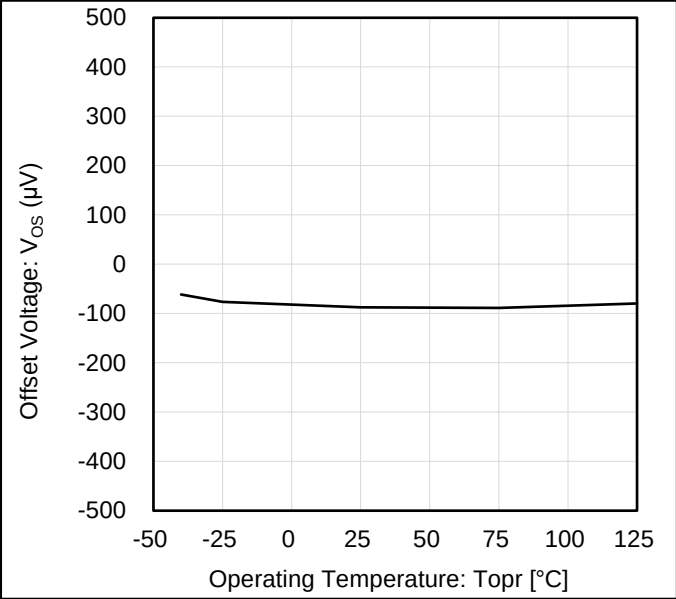


Figure 2. Offset Voltage vs Operating Temperature

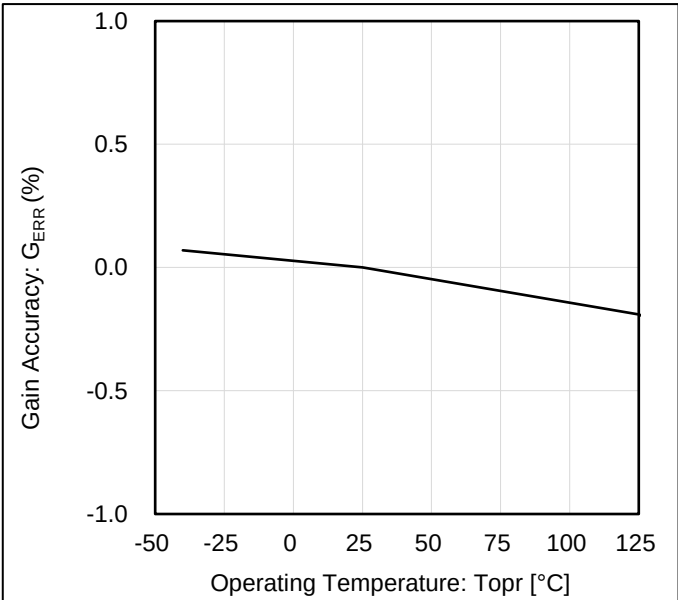


Figure 3. Gain Accuracy vs Operating Temperature

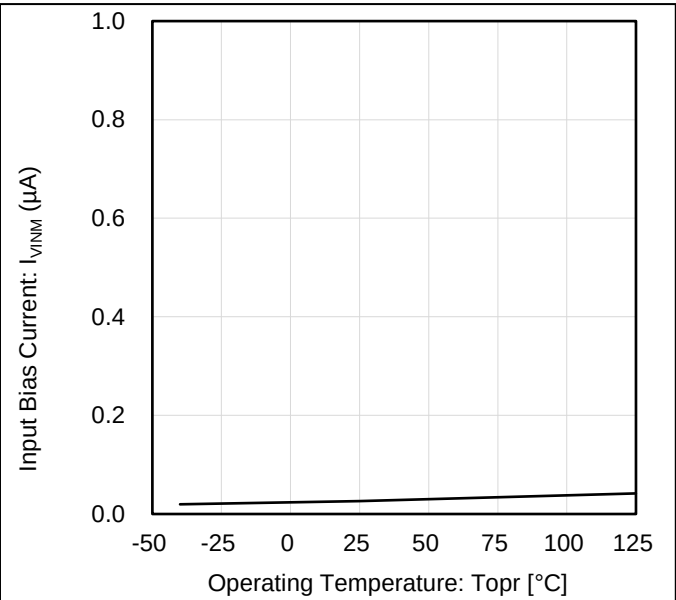


Figure 4. Input Bias Current vs Operating Temperature

Typical Performance Curves - continued

(Unless otherwise specified $V_{DD} = 5\text{ V}$, $V_{CM} = 12\text{ V}$, $V_{SENSE} = (V_{VINP} - V_{VINM})$, $T_a = 25\text{ }^{\circ}\text{C}$)

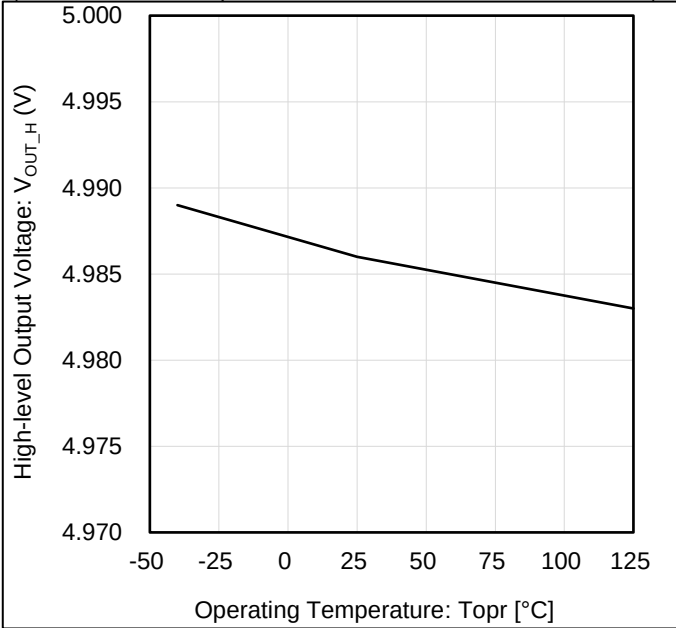


Figure 5. High-level Output Voltage vs Operating Temperature

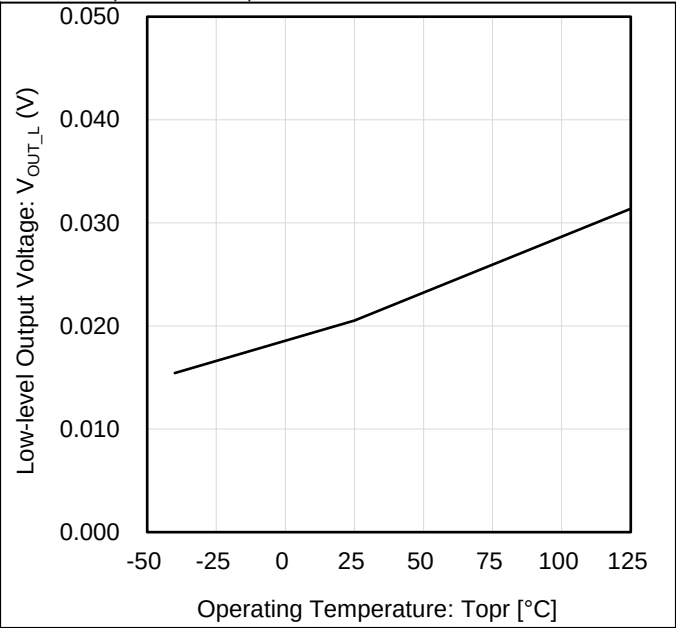


Figure 6. Low-level Output Voltage vs Operating Temperature

Basic Explanation

This IC has the structure specialized for Current Sense Amplifier and has the following features. Common mode voltage range is maximum 26 V with VDD of maximum 5.5 V, therefore it is possible to detect the current flowing in a power supply line exceeding VDD voltage. And its input bias current is very low.

This IC amplifies the voltage difference across the shunt resistor between VINP and VINM and outputs a voltage with the GND pin as reference voltage.

If the current flows from VINP to VINM, OUT pin voltage is higher than GND pin voltage. If the current flows from VINM to VINP, OUT pin voltage is clipped to GND pin voltage.

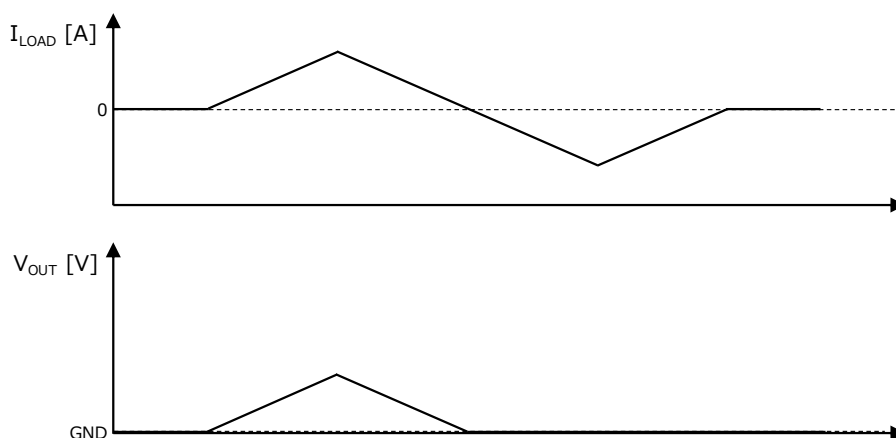
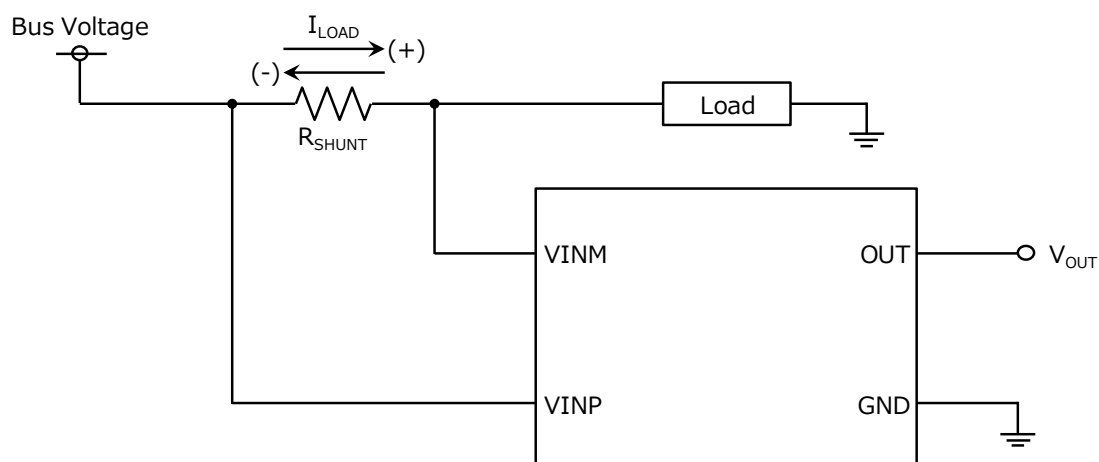


Figure 7. Basic Explanation

V_{OUT} is calculated by the below formula.

$$V_{OUT} = R_{SHUNT} \times I_{LOAD} \times GAIN$$

Where,

R_{SHUNT} is the Shunt resistance

I_{LOAD} is the Load current

$GAIN$ is the Gain of Current Sense Amplifier

Also, V_{OUT} needs to be $GND < V_{OUT} < VDD$.

V_{OUT} is clipped to Low-level Output Voltage (V_{OUT_L}) when it's under GND.

V_{OUT} is clipped to High-level Output Voltage (V_{OUT_H}) when it's over VDD.

Basic Explanation - continued

Input pin VINP and VINM needs to be connected to IC as close as possible in order to minimize the influence on series resistance of shunt resistor.

For stability, dispose and connect a bypass capacitor for removing power source noise close to IC.

Selection of shunt resistor

Shunt resistor R_{SHUNT} should be selected considering the accuracy of measuring current and the maximum power dissipation according to an application.

If the value of shunt resistor is high, it minimizes the influence of offset and increases the accuracy of measuring current.

If the value of shunt resistor is low, it reduces the power dissipation of VDD.

Shunt resistor value is calculated by below formula.

$$R_{SHUNT} < VDD / (abs(I_{LOADMAX}) \times GAIN)$$

Where

VDD is the Power Supply

$abs(I_{LOADMAX})$ is the Maximum of load current (absolute value)

Control Sequence

- 1. Control Sequence
 - 1.1 Power supply start-up sequence

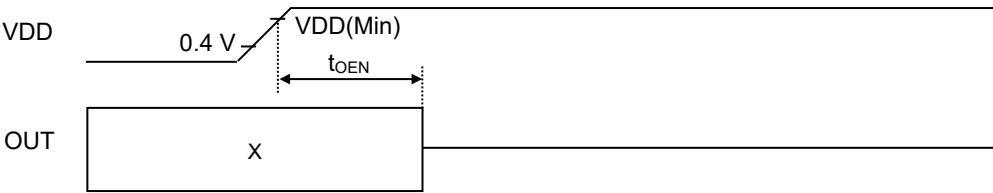


Figure 8. Timing Chart at Power ON

Stable time of OUT(tOEN) should be more than 1 ms.

- 1.2 Power supply end sequence

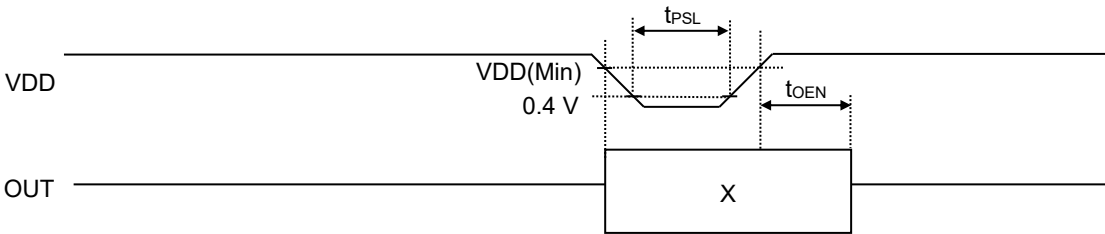


Figure 9. Timing Chart at Power OFF

Power off time(tPSL) should be more than 1 ms.
If VDD voltage is under the recommended operating condition, LSI is unstable state. In that case, set Power OFF and ON again. When the power is ON again, the period of VDD<0.4 V should be more than tPSL.

I/O Equivalence Circuits

Pin Name	Equivalent Circuit Diagram	Pin Name	Equivalent Circuit Diagram
OUT1 OUT2		VINP1 VINM1 VINP2 VINM2	

Operational Notes

1. Reverse Connection of Power Supply

Connecting the power supply in reverse polarity can damage the IC. Take precautions against reverse polarity when connecting the power supply, such as mounting an external diode between the power supply and the IC's power supply pins.

2. Power Supply Lines

Design the PCB layout pattern to provide low impedance supply lines. Furthermore, connect a capacitor to ground at all power supply pins. Consider the effect of temperature and aging on the capacitance value when using electrolytic capacitors.

3. Ground Voltage

Ensure that no pins are at a voltage below that of the ground pin at any time, even during transient condition.

4. Ground Wiring Pattern

When using both small-signal and large-current ground traces, the two ground traces should be routed separately but connected to a single ground at the reference point of the application board to avoid fluctuations in the small-signal ground caused by large currents. Also ensure that the ground traces of external components do not cause variations on the ground voltage. The ground lines must be as short and thick as possible to reduce line impedance.

5. Recommended Operating Conditions

The function and operation of the IC are guaranteed within the range specified by the recommended operating conditions. The characteristic values are guaranteed only under the conditions of each item specified by the electrical characteristics.

6. Inrush Current

When power is first supplied to the IC, it is possible that the internal logic may be unstable and inrush current may flow instantaneously due to the internal powering sequence and delays, especially if the IC has more than one power supply. Therefore, give special consideration to power coupling capacitance, power wiring, width of ground wiring, and routing of connections.

7. Testing on Application Boards

When testing the IC on an application board, connecting a capacitor directly to a low-impedance output pin may subject the IC to stress. Always discharge capacitors completely after each process or step. The IC's power supply should always be turned off completely before connecting or removing it from the test setup during the inspection process. To prevent damage from static discharge, ground the IC during assembly and use similar precautions during transport and storage.

8. Inter-pin Short and Mounting Errors

Ensure that the direction and position are correct when mounting the IC on the PCB. Incorrect mounting may result in damaging the IC. Avoid nearby pins being shorted to each other especially to ground, power supply and output pin. Inter-pin shorts could be due to many reasons such as metal particles, water droplets (in very humid environment) and unintentional solder bridge deposited in between pins during assembly to name a few.

9. Unused Input Pins

Input pins of an IC are often connected to the gate of a MOS transistor. The gate has extremely high impedance and extremely low capacitance. If left unconnected, the electric field from the outside can easily charge it. The small charge acquired in this way is enough to produce a significant effect on the conduction through the transistor and cause unexpected operation of the IC. So unless otherwise specified, unused input pins should be connected to the power supply or ground line.

Operational Notes - continued

10. Regarding the Input Pin of the IC

This monolithic IC contains P⁺ isolation and P substrate layers between adjacent elements in order to keep them isolated. P-N junctions are formed at the intersection of the P layers with the N layers of other elements, creating a parasitic diode or transistor. For example (refer to figure below):

When GND > Pin A and GND > Pin B, the P-N junction operates as a parasitic diode.

When GND > Pin B, the P-N junction operates as a parasitic transistor.

Parasitic diodes inevitably occur in the structure of the IC. The operation of parasitic diodes can result in mutual interference among circuits, operational faults, or physical damage. Therefore, conditions that cause these diodes to operate, such as applying a voltage lower than the GND voltage to an input pin (and thus to the P substrate) should be avoided.

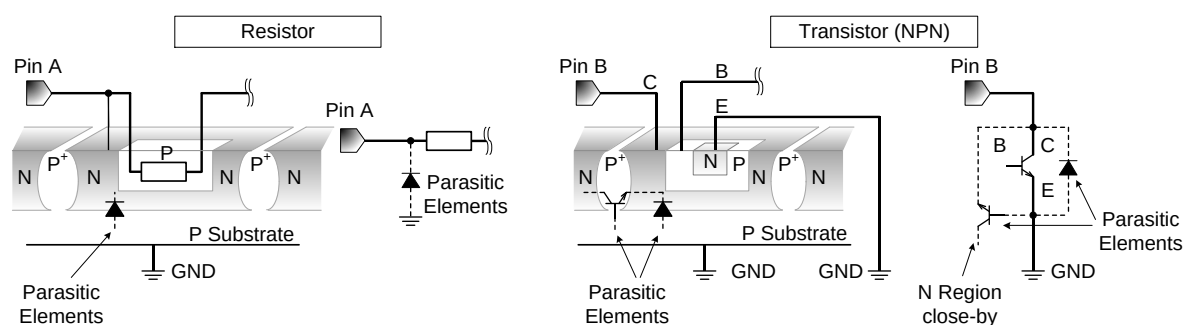


Figure 10. Example of Monolithic IC Structure

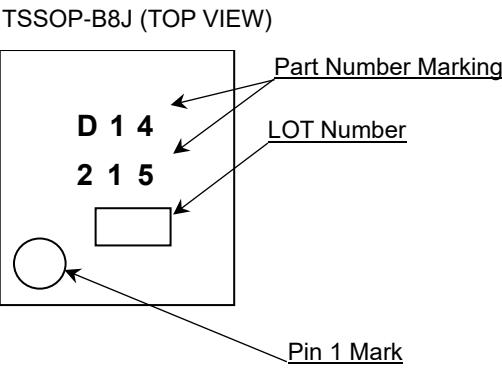
11. Ceramic Capacitor

When using a ceramic capacitor, determine a capacitance value considering the change of capacitance with temperature and the decrease in nominal capacitance due to DC bias and others.

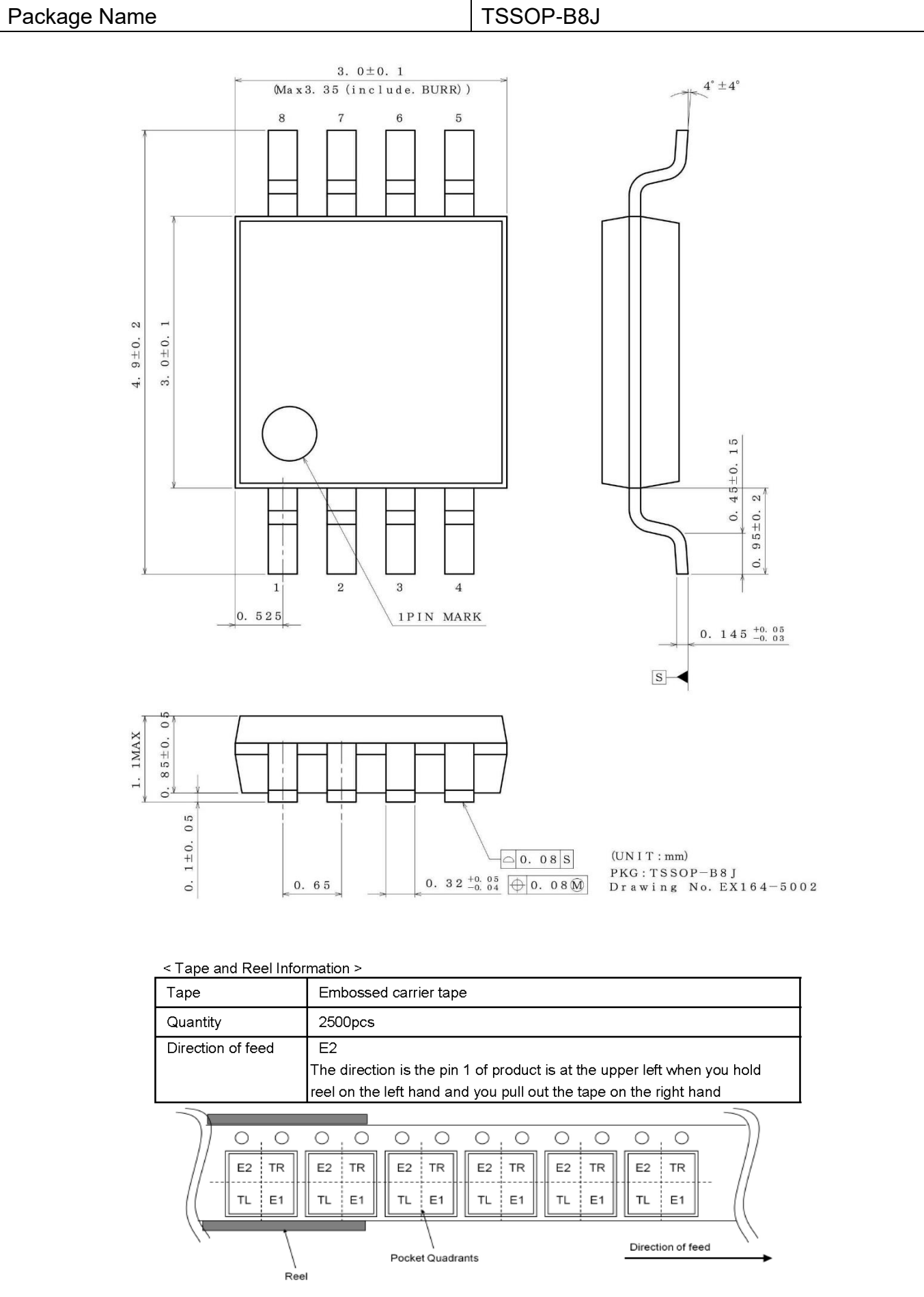
Ordering Information

B	D	1	4	2	1	5	F	V	J	-	L	A	E	2
Package FVJ: TSSOP-B8J										Product Class LA for Industrial Applications Packaging and forming specification E2: Embossed tape and reel				

Marking Diagram



Physical Dimension and Packing Information



Revision History

Date	Revision	Changes
06.Sep.2022	001	New Release
28.Jun.2024	002	Revision up only

Notice

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(Note1) Medical Equipment Classification of the Specific Applications

JAPAN	USA	EU	CHINA
CLASS III	CLASS III	CLASS II b	CLASS III
CLASS IV		CLASS III	

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 - [h] Use of the Products in places subject to dew condensation
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6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
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8. Confirm that operation temperature is within the specified range described in the product specification.
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2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

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